

Abstract

Method for surface treatment of a substrate (B), in particular as a preparatory step for a method for bonding the substrate to a further substrate, comprising

- 5 - providing the substrate (B) with a bonding surface intended for bonding,
- treatment (100) of the substrate (B) at least in a part of the bonding surface, forming an amorphous layer (C) having a first thickness (D1), primary particle radiation preferably being used to form the amorphous layer (C), and
- layer thickness reduction (200) of the amorphous layer (C), more preferably to a
- 10 second thickness (D2).

[Fig. 2]